

InvenSense IDG-600/650 2-Axis Gyroscope

Reverse Costing Analysis

by System Plus Consulting

Physical Analysis of the Device

Step by Step Reconstruction of the Process Flow

Cost of Manufacturing and Estimation of Selling Price

System Plus Consulting is proud to publish the reverse costing report of the Dual-Axis MEMS Gyroscope IDG-600/650 supplied by InvenSense.

The IDG-600, integrated in the Nintendo Wii Motion Plus accessory, and its standard variation the IDG-650 share the same hardware. The components are manufactured using a three-bonded-wafer process: a thin sensor wafer and a protective cap wafer processed with bulk micromachining and an ASIC wafer for signal conditioning.

The IDG-600/650 gyroscopes are suitable for high performance motion sensing game controllers, pointing devices, multimedia remotes and computer mice applications.

This report provides complete teardown of the MEMS Gyroscope with:

- Detailed photos
- Material analysis
- Schematic assembly description
- Manufacturing Process Flow
- In-depth economical analysis
- Manufacturing cost breakdown
- Selling price estimation



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The present document is valid till 1st November 2010.

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